

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

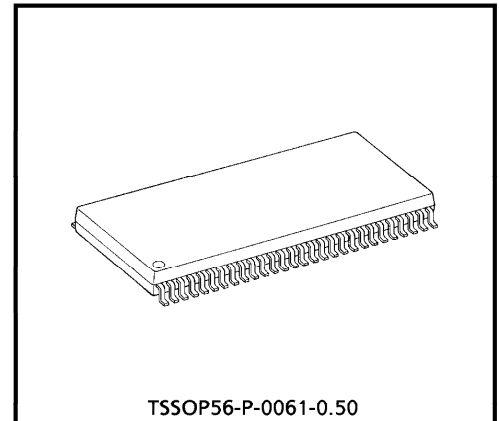
TC74VCX16823FT**LOW-VOLTAGE 18-BIT D-TYPE FLIP-FLOP
WITH 3.6 V TOLERANT INPUTS AND OUTPUTS**

The TC74VCX16823FT is a high performance CMOS 18-bit D-TYPE FLIP-FLOP. Designed for use in 1.8, 2.5 or 3.3 Volt systems, it achieves high speed operation while maintaining the CMOS low power dissipation. It is also designed with over voltage tolerant inputs and outputs up to 3.6V.

The TC74VCX16823FT can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable ($\overline{\text{CKEN}}$) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking $\overline{\text{CKEN}}$ high disables the clock buffer, thus latching the outputs. Taking the clear ($\overline{\text{CLR}}$) input low causes the Q outputs to go low independently of the clock.

When the $\overline{\text{OE}}$ input is high, the outputs are in a high impedance state. This device is designed to be used with 3-state memory address drivers, etc.

All inputs are equipped with protection circuits against static discharge.



TSSOP56-P-0061-0.50

Weight : 0.25 g (Typ.)

FEATURES

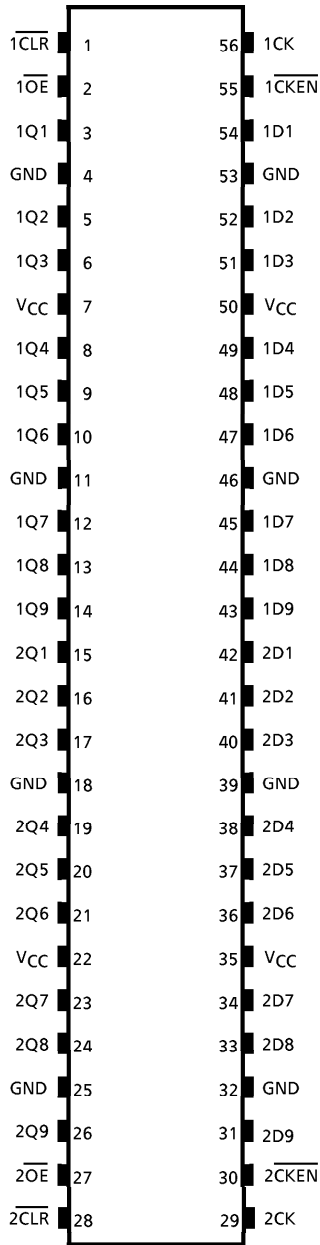
- Low Voltage Operation : $V_{CC} = 1.8\sim 3.6\text{ V}$
- High Speed Operation : $t_{pd} = 3.5\text{ ns (max) at } V_{CC} = 3.0\sim 3.6\text{ V}$
 : $t_{pd} = 4.4\text{ ns (max) at } V_{CC} = 2.3\sim 2.7\text{ V}$
 : $t_{pd} = 8.8\text{ ns (max) at } V_{CC} = 1.8\text{ V}$
- 3.6V Tolerant inputs and outputs.
- Output Current : $I_{OH}/I_{OL} = \pm 24\text{ mA (min) at } V_{CC} = 3.0\text{ V}$
 : $I_{OH}/I_{OL} = \pm 18\text{ mA (min) at } V_{CC} = 2.3\text{ V}$
 : $I_{OH}/I_{OL} = \pm 6\text{ mA (min) at } V_{CC} = 1.8\text{ V}$
- Latch-up Performance : $\pm 300\text{ mA}$
- ESD Performance : Human Body Model $> \pm 2000\text{ V}$
 : Machine Model $> \pm 200\text{ V}$
- Package : TSSOP
 (Thin Shrink Small Outline Package)
- Power Down Protection is provided on all inputs and outputs.
- Supports live insertion / withdrawal (Note 1)

(Note 1) : To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

980910EBA2

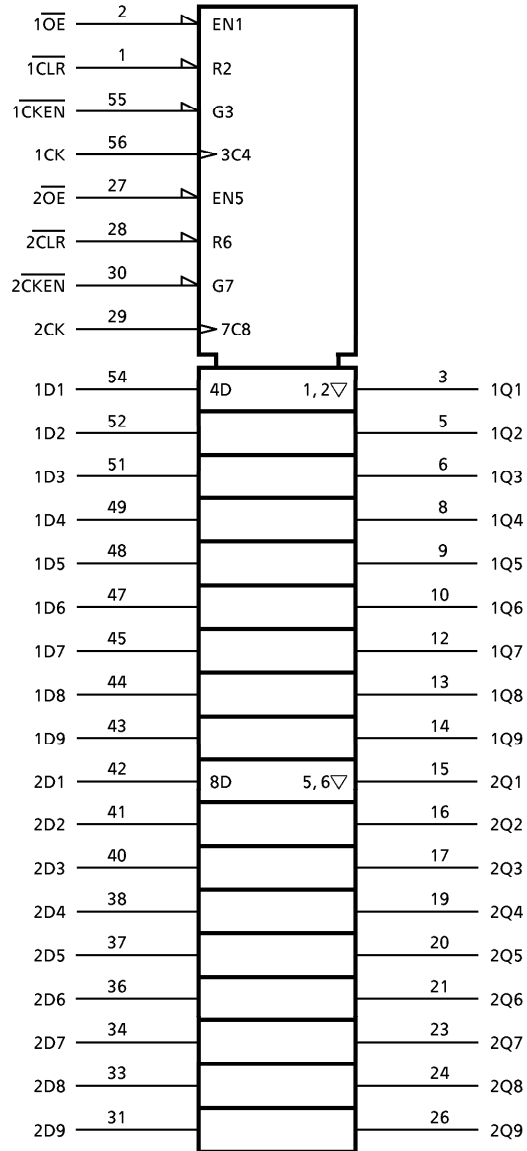
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PIN ASSIGNMENT



(TOP VIEW)




SYMBOL



980910EBA2'

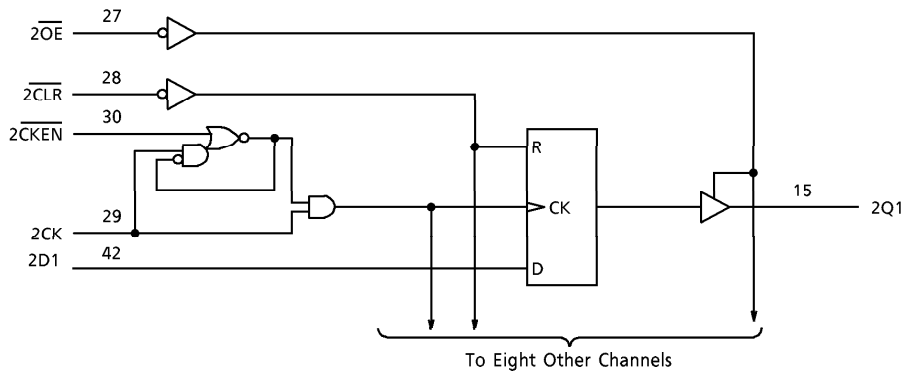
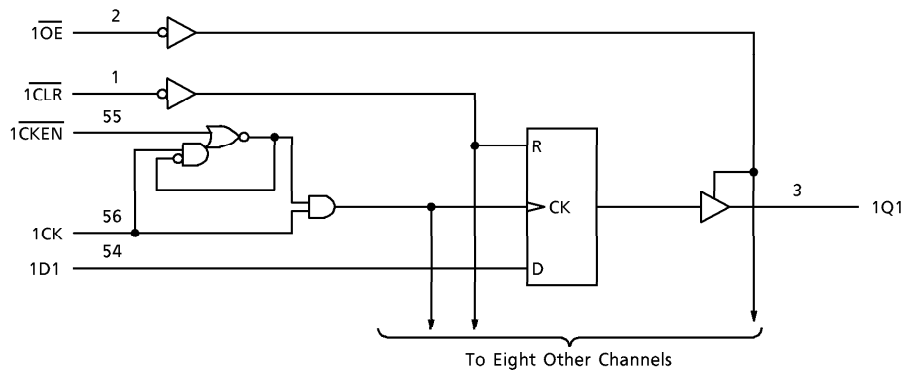
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TRUTH TABLE (each 9-bit flip flop)

INPUTS					OUTPUTS
\overline{OE}	\overline{CLR}	\overline{CKEN}	CK	D	Q
L	L	X	X	X	L
L	H	L		H	H
L	H	L		L	L
L	H	L		X	Q0
L	H	H	X	X	Q0
H	X	X	X	X	Z

X : Don't Care
 Z : High impedance
 Qn : No change

SYSTEM DIAGRAM



MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT
Power Supply Voltage	V_{CC}	-0.5~4.6	V
DC Input Voltage	V_{IN}	-0.5~4.6	V
DC Output Voltage	V_{OUT}	-0.5~4.6 (Note 1)	V
		-0.5~ V_{CC} + 0.5 (Note 2)	
Input Diode Current	I_{IK}	- 50	mA
Output Diode Current	I_{OK}	± 50 (Note 3)	mA
DC Output Current	I_{OUT}	± 50	mA
Power Dissipation	P_D	400	mW
DC V_{CC} / Ground Current Per Supply Pin	I_{CC} / I_{GND}	± 100	mA
Storage Temperature	T_{stg}	- 65~150	°C

(Note 1) : Off-State

(Note 2) : High or Low State. I_{OUT} absolute maximum rating must be observed.

(Note 3) : $V_{OUT} < GND$, $V_{OUT} > V_{CC}$

RECOMMENDED OPERATING RANGE

PARAMETER	SYMBOL	RATING	UNIT
Supply Voltage	V_{CC}	1.8~3.6	V
		1.2~3.6 (Note 4)	
Input Voltage	V_{IN}	-0.3~3.6	V
Output Voltage	V_{OUT}	0~3.6 (Note 5)	V
		0~ V_{CC} (Note 6)	
Output Current	I_{OH} / I_{OL}	± 24 (Note 7)	mA
		± 18 (Note 8)	
		± 6 (Note 9)	
Operating Temperature	T_{opr}	- 40~85	°C
Input Rise And Fall Time	dt / dv	0~10 (Note 10)	ns / V

(Note 4) : Data Retention Only

(Note 5) : Off-State

(Note 6) : High or Low State

(Note 7) : $V_{CC} = 3.0\sim 3.6\text{ V}$

(Note 8) : $V_{CC} = 2.3\sim 2.7\text{ V}$

(Note 9) : $V_{CC} = 1.8\text{ V}$

(Note 10) : $V_{IN} = 0.8\sim 2.0\text{ V}$, $V_{CC} = 3.0\text{ V}$

ELECTRICAL CHARACTERISTICS

DC characteristics (Ta = -40~85°C, 2.7 V < VCC ≤ 3.6 V)

PARAMETER		SYMBOL	TEST CONDITION		VCC (V)	MIN	MAX	UNIT
Input Voltage	"H" Level	V _{IH}			2.7~3.6	2.0	—	V
	"L" Level	V _{IL}			2.7~3.6	—	0.8	
Output Voltage	"H" Level	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -100 μA	2.7~3.6	V _{CC} - 0.2	—	V
				I _{OH} = -12 mA	2.7	2.2	—	
				I _{OH} = -18 mA	3.0	2.4	—	
				I _{OH} = -24 mA	3.0	2.2	—	
	"L" Level	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 100 μA	2.7~3.6	—	0.2	
				I _{OL} = 12 mA	2.7	—	0.4	
				I _{OL} = 18 mA	3.0	—	0.4	
				I _{OL} = 24 mA	3.0	—	0.55	
Input Leakage Current		I _{IIN}	V _{IN} = 0~3.6 V		2.7~3.6	—	± 5.0	μA
3-State Output Off-State Current		I _{OZ}	V _{IN} = V _{IH} or V _{IL} V _{OUT} = 0~3.6 V		2.7~3.6	—	± 10.0	μA
Power Off Leakage Current		I _{OFF}	V _{IN} , V _{OUT} = 0~3.6 V		0	—	10.0	μA
Quiescent Supply Current		I _{CC}	V _{IN} = V _{CC} or GND		2.7~3.6	—	20.0	μA
			V _{CC} ≤ (V _{IN} , V _{OUT}) ≤ 3.6 V		2.7~3.6	—	± 20.0	
Increase In I _{CC} Per Input		ΔI _{CC}	V _{IH} = V _{CC} - 0.6 V		2.7~3.6	—	750	μA

ELECTRICAL CHARACTERISTICS

DC characteristics ($T_a = -40\sim 85^\circ\text{C}$, $2.3\text{ V} \leq V_{CC} \leq 2.7\text{ V}$)

PARAMETER		SYMBOL	TEST CONDITION		V _{CC} (V)	MIN	MAX	UNIT
Input Voltage	"H" Level	V _{IH}			2.3~2.7	1.6	—	V
	"L" Level	V _{IL}			2.3~2.7	—	0.7	
Output Voltage	"H" Level	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -100 μA	2.3~2.7	V _{CC} - 0.2	—	V
				I _{OH} = -6 mA	2.3	2.0	—	
				I _{OH} = -12 mA	2.3	1.8	—	
				I _{OH} = -18 mA	2.3	1.7	—	
	"L" Level	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 100 μA	2.3~2.7	—	0.2	
				I _{OL} = 12 mA	2.3	—	0.4	
			I _{OL} = 18 mA	2.3	—	0.6		
Input Leakage Current		I _{IN}	V _{IN} = 0~3.6 V		2.3~2.7	—	±5.0	μA
3-State Output Off-State Current		I _{OZ}	V _{IN} = V _{IH} or V _{IL} V _{OUT} = 0~3.6 V		2.3~2.7	—	±10.0	μA
Power Off Leakage Current		I _{OFF}	V _{IN} , V _{OUT} = 0~3.6 V		0	—	10.0	μA
Quiescent Supply Current		I _{CC}	V _{IN} = V _{CC} or GND		2.3~2.7	—	20.0	μA
			V _{CC} ≤ (V _{IN} , V _{OUT}) ≤ 3.6 V		2.3~2.7	—	±20.0	

ELECTRICAL CHARACTERISTICS

DC characteristics ($T_a = -40\sim 85^\circ\text{C}$, $1.8\text{ V} \leq V_{CC} < 2.3\text{ V}$)

PARAMETER		SYMBOL	TEST CONDITION		V _{CC} (V)	MIN	MAX	UNIT
Input Voltage	"H" Level	V _{IH}			1.8~2.3	0.7 × V _{CC}	—	V
	"L" Level	V _{IL}			1.8~2.3	—	0.2 × V _{CC}	
Output Voltage	"H" Level	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -100 μA	1.8	V _{CC} - 0.2	—	V
				I _{OH} = -6 mA	1.8	1.4	—	
	"L" Level	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 100 μA	1.8	—	0.2	
				I _{OL} = 6 mA	1.8	—	0.3	
Input Leakage Current		I _{IN}	V _{IN} = 0~3.6 V		1.8	—	±5.0	μA
3-State Output Off-State Current		I _{OZ}	V _{IN} = V _{IH} or V _{IL} V _{OUT} = 0~3.6 V		1.8	—	±10.0	μA
Power Off Leakage Current		I _{OFF}	V _{IN} , V _{OUT} = 0~3.6 V		0	—	10.0	μA
Quiescent Supply Current		I _{CC}	V _{IN} = V _{CC} or GND		1.8	—	20.0	μA
			V _{CC} ≤ (V _{IN} , V _{OUT}) ≤ 3.6 V		1.8	—	±20.0	

AC characteristics (Ta = -40~85°C, Input $t_r = t_f = 2.0$ ns, $C_L = 30$ pF, $R_L = 500$ Ω)

PARAMETER	SYMBOL	TEST CONDITION	VCC (V)	MIN	MAX	UNIT
Maximum Clock Frequency	f _{MAX}	(Fig.1, 2)	1.8	100	—	MHz
			2.5 ± 0.2	200	—	
			3.3 ± 0.3	250	—	
Propagation Delay Time (CK-Q)	t _{pLH} t _{pHL}	(Fig.1, 2)	1.8	1.5	8.8	ns
			2.5 ± 0.2	0.8	4.4	
			3.3 ± 0.3	0.6	3.5	
Propagation Delay Time (CLR-Q)	t _{pHL}	(Fig.1, 3)	1.8	1.5	9.2	ns
			2.5 ± 0.2	0.8	4.6	
			3.3 ± 0.3	0.6	3.7	
3-State Output Enable Time	t _{pZL} t _{pZH}	(Fig.1, 4)	1.8	1.5	9.8	ns
			2.5 ± 0.2	0.8	4.9	
			3.3 ± 0.3	0.6	3.8	
3-State Output Disable Time	t _{pLZ} t _{pHZ}	(Fig.1, 4)	1.8	1.5	7.6	ns
			2.5 ± 0.2	0.8	4.2	
			3.3 ± 0.3	0.6	3.7	
Minimum Pulse Width (CK, CLR)	t _w (H) t _w (L)	(Fig.1, 2, 3)	1.8	4.0	—	ns
			2.5 ± 0.2	1.5	—	
			3.3 ± 0.3	1.5	—	
Minimum Set-up Time (D, CKEN)	t _s	(Fig.1, 2, 5)	1.8	2.5	—	ns
			2.5 ± 0.2	1.5	—	
			3.3 ± 0.3	1.5	—	
Minimum Hold Time (D, CKEN)	t _h	(Fig.1, 2, 5)	1.8	1.0	—	ns
			2.5 ± 0.2	1.0	—	
			3.3 ± 0.3	1.0	—	
Minimum Removal Time	t _{rem}	(Fig.1, 6)	1.8	4.0	—	ns
			2.5 ± 0.2	2.0	—	
			3.3 ± 0.3	2.0	—	
Output to Output Skew	t _{osLH} t _{osHL}	(Note 11)	1.8	—	0.5	ns
			2.5 ± 0.2	—	0.5	
			3.3 ± 0.3	—	0.5	

For $C_L = 50$ pF, add approximately 300 ps to the AC maximum specification.

(Note 11) : Parameter guaranteed by design.

$$(t_{osLH} = |t_{pLHm} - t_{pLHn}|, t_{osHL} = |t_{pHLm} - t_{pHLn}|)$$

Dynamic switching characteristics (Ta = 25°C, Input tr = tf = 2.0 ns, CL = 30 pF)

PARAMETER	SYMBOL	TEST CONDITION	VCC (V)	TYP.	UNIT
Quiet Output Maximum Dynamic VOL	VOLP	V _{IH} = 1.8 V, V _{IL} = 0 V (Note 12)	1.8	0.25	V
		V _{IH} = 2.5 V, V _{IL} = 0 V (Note 12)	2.5	0.6	
		V _{IH} = 3.3 V, V _{IL} = 0 V (Note 12)	3.3	0.8	
Quiet Output Minimum Dynamic VOL	VOLV	V _{IH} = 1.8 V, V _{IL} = 0 V (Note 12)	1.8	-0.25	V
		V _{IH} = 2.5 V, V _{IL} = 0 V (Note 12)	2.5	-0.6	
		V _{IH} = 3.3 V, V _{IL} = 0 V (Note 12)	3.3	-0.8	
Quiet Output Minimum Dynamic VOH	VOHV	V _{IH} = 1.8 V, V _{IL} = 0 V (Note 12)	1.8	1.5	V
		V _{IH} = 2.5 V, V _{IL} = 0 V (Note 12)	2.5	1.9	
		V _{IH} = 3.3 V, V _{IL} = 0 V (Note 12)	3.3	2.2	

(Note 12) : Parameter guaranteed by design.

Capacitive characteristics (Ta = 25°C)

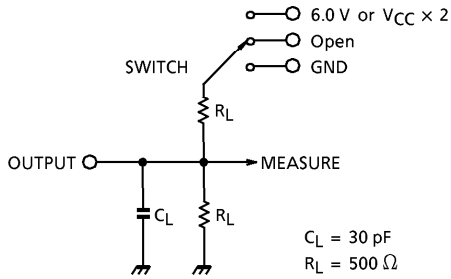
PARAMETER	SYMBOL	TEST CONDITION	VCC (V)	TYP.	UNIT
Input Capacitance	C _{IN}		1.8, 2.5, 3.3	6	pF
Output Capacitance	C _O		1.8, 2.5, 3.3	7	pF
Power Dissipation Capacitance	C _{PD}	f _{IN} = 10 MHz (Note 13)	1.8, 2.5, 3.3	20	pF

(Note 13) : C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 18 (\text{per bit})$$

TEST CIRCUIT
Fig.1



PARAMETER	SWITCH
t_{pLH}, t_{pHL}	Open
t_{pLZ}, t_{pZL}	6.0 V @ $V_{CC} = 3.3 \pm 0.3 \text{ V}$ $V_{CC} \times 2$ @ $V_{CC} = 2.5 \pm 0.2 \text{ V}$ @ $V_{CC} = 1.8 \text{ V}$
t_{pHZ}, t_{pZH}	GND

AC WAVEFORM

Fig.2 $t_{pLH}, t_{pHL}, t_w, t_s, t_h$

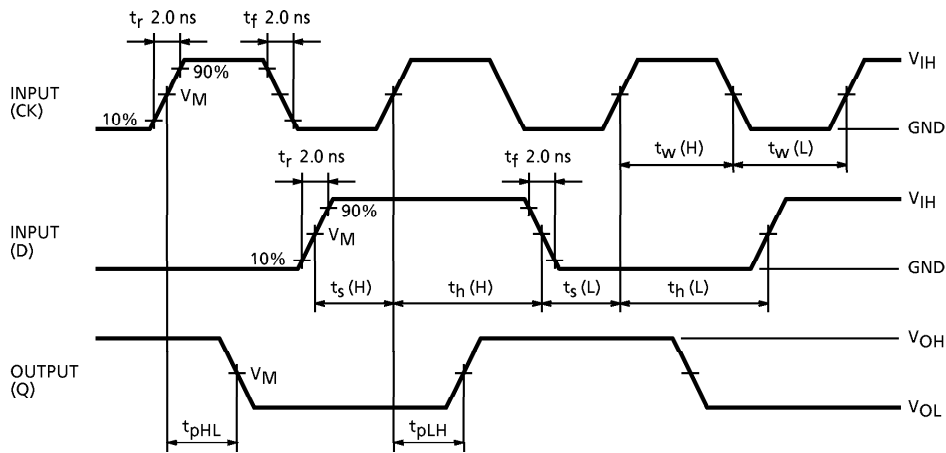


Fig.3 t_{pHL}

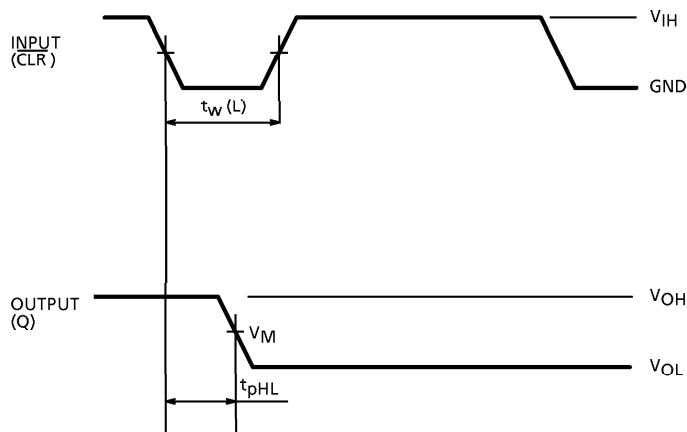
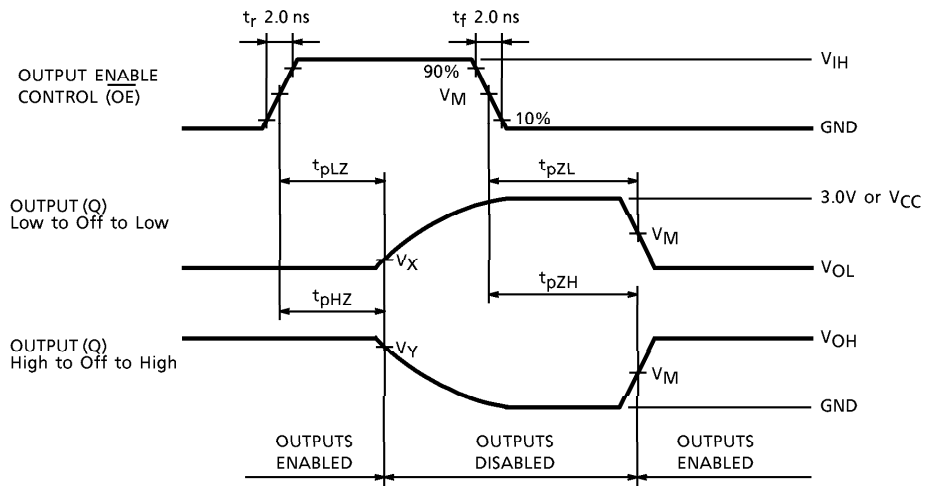


Fig.4 t_{pLZ} , t_{pHZ} , t_{pZL} , t_{pZH}



SYMBOL	V _{CC}		
	3.3 ± 0.3 V	2.5 ± 0.2 V	1.8 V
V _{IH}	2.7 V	V _{CC}	V _{CC}
V _M	1.5 V	V _{CC} / 2	V _{CC} / 2
V _X	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V
V _Y	V _{OH} - 0.3 V	V _{OH} - 0.15 V	V _{OH} - 0.15 V

Fig.5 t_s , t_h

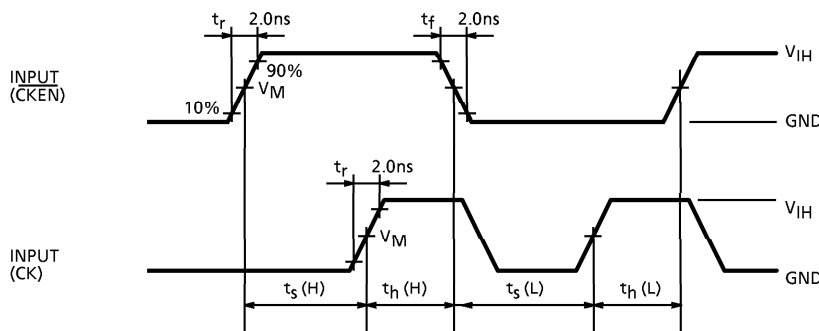
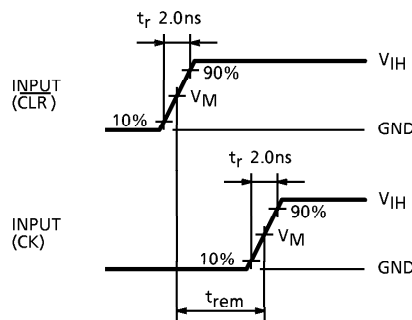


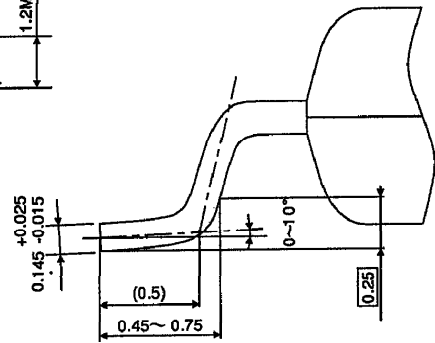
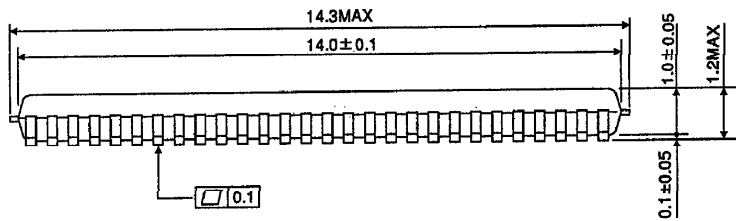
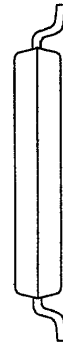
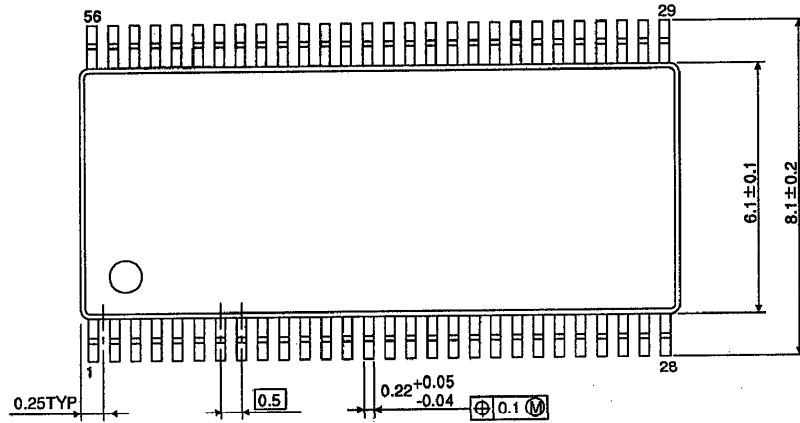
Fig.6 t_{rem}



PACKAGE DIMENSIONS

TSSOP56-P-0061-0.50

Unit : mm



Weight : 0.25 g (Typ.)